CMSD6001 CMSD6001A CMSD6001C CMSD6001S

SURFACE MOUNT ULTRA LOW LEAKAGE SILICON SWITCHING DIODES



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DESCRIPTION:

The CENTRAL SEMICONDUCTOR CMSD6001 SERIES are silicon switching diodes manufactured by the epitaxial planar process, epoxy molded in a SUPERmini[™] surface mount package, designed for switching applications requiring an extremely low leakage diode.

 Device 	IS	Halogen	⊢ree	bу	design	

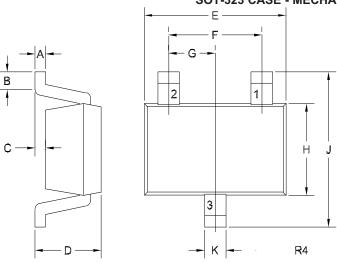
CMSD6001:SINGLECMSD6001A:DUAL, COMMON ANODECMSD6001C:DUAL, COMMON CATHODECMSD6001S:DUAL, IN-SERIES	MARKING CO MARKING CO MARKING CO MARKING CO	DDE: 61A DDE: 61C	
MAXIMUM RATINGS: (T _A =25°C) Continuous Reverse Voltage	SYMBOL V _R	75	UNITS V
Peak Repetitive Reverse Voltage	V _{RRM}	100	V
Continuous Forward Current	١ _F	250	mA
Peak Repetitive Forward Current	IFRM	250	mA
Peak Forward Surge Current, tp=1.0µs	IFSM	4.0	А
Peak Forward Surge Current, tp=1.0s	IFSM	1.0	А
Power Dissipation	PD	275	mW
Operating and Storage Junction Temperature	TJ, T _{stg}	-65 to +150	°C
Thermal Resistance	Θ _{JA}	455	°C/W
ELECTRICAL CHARACTERISTICS PER DIODE	(T _A =25°C unless	otherwise noted)	

JNITS
pА
V
V
V
V
pF
μs



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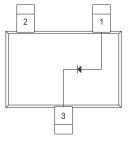
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DIMENSIONS							
	INC	HES	MILLIMETERS				
SYMBOL	MIN	MAX	MIN	MAX			
А	0.002	0.008	0.05	0.20			
В	0.004	-	0.10	-			
С	-	0.004	-	0.10			
D	0.031	0.043	0.80	1.10			
E	0.071	0.087	1.80	2.20			
F	0.051		1.30				
G	0.026		0.65				
Н	0.045	0.053	1.15	1.35			
J	0.079	0.094	2.00	2.40			
K	0.008	0.016	0.20	0.40			
SOT-323 (REV: R4)							

SOT-323 CASE - MECHANICAL OUTLINE

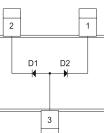




CMSD6001

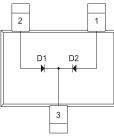
LEAD CODE: 1) Anode 2) NC 3) Cathode

MARKING CODE: 6C1



CMSD6001A LEAD CODE: 1) Cathode D2 2) Cathode D1 3) Anode D1, D2

MARKING CODE: 61A



CMSD6001C LEAD CODE: 1) Anode D2

2) Anode D1 3) Cathode D1, D2

MARKING CODE: 61C

CMSD6001S

- LEAD CODE: 1) Anode D2
- 2) Cathode D1
- 3) Anode D1, Cathode D2

MARKING CODE: 61S

OUTSTANDING SUPPORT AND SUPERIOR SERVICES

PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- · Consolidated shipping options

DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2nd day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities

ss your design challenges.

· Custom product packing

- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- · Application and design sample kits

Custom bar coding for shipments

Custom product and package development

REQUESTING PRODUCT PLATING

- 1. If requesting Tin/Lead plated devices, add the suffix "TIN/LEAD" to the part number when ordering (example: 2N2222A TIN/LEAD).
- If requesting Lead (Pb) Free plated devices, add the suffix "PBFREE" to the part number when ordering (example: 2N2222A PBFREE).

CONTACT US

Corporate Headquarters & Customer Support Team

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